

#### **Product Summary**

BV <sub>DSS</sub>	Rds(on) Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C	
	87mΩ @ V <sub>GS</sub> = 10V	2.7A	
60V	100mΩ @ V <sub>GS</sub> = 4.5V	2.5A	

## **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

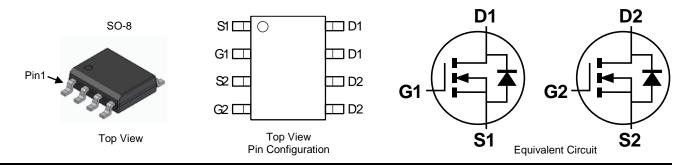
#### **Features and Benefits**

- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN6070SSDQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

#### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)



### Ordering Information (Note 4)

Case	Packaging
SO-8	2,500/Tape & Reel

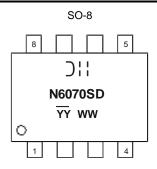
No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**

Notes:



); | = Manufacturer's Marking N6070SD = Product Type Marking Code  $\overrightarrow{YY}WW$  = Date Code Marking  $\overrightarrow{YY}$  = Year (ex: 20 = 2020) WW = Week (01 to 53)

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# Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	60	V
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	2.7 2.1	A
Maximum Continuous Body Diode Forward Current (Note 6)			ls	2.7	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	12	A
Avalanche Current (Note 7) L=0.1mH			las	10	A
Avalanche Energy (Note 7) L=0.1mH			Eas	5	mJ

## Thermal Characteristics (@T<sub>A=</sub> +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Total Power Dissipation (Note 5)		PD	1.2	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>0JA</sub>	104	°C/W	
Total Power Dissipation (Note 6)		PD	1.5	W	
Thermal Resistance, Junction to Ambient (Note 6) Steady State		R <sub>θJA</sub>	83	°C/W	
Thermal Resistance, Junction to Case (Note 6)	Rejc	14.5			
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

## Electrical Characteristics (@TA= +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)			1	r		
Drain-Source Breakdown Voltage	BVDSS	60	—	—	V	$I_D = 250 \mu A, V_{GS} = 0 V$
Zero Gate Voltage Drain Current	IDSS		—	1	μA	VDS= 60V, VGS= 0V
Gate-Source Leakage	lgss	_	_	±100	nA	$V_{GS}=\pm 16V$ , $V_{DS}=0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	VGS(TH)	1.0	_	3.0	V	ID= 250µA, VDS= VGS
Static Drain-Source On-Resistance	Proven		68	87	mΩ	VGS= 10V, ID= 4.5A
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	70	100	11122	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.5A
Diode Forward Voltage	Vsd	_	0.75	1.1	V	Is= 12A, V <sub>GS</sub> = 0V
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	_	588			V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V f= 1MHz
Output Capacitance	Coss	—	26.5	_	pF	
Reverse Transfer Capacitance	Crss	_	20	_		
Gate Resistance	Rg	_	1.5	—	Ω	VGS= 0V, VDS= 0V, f=1MHz
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	5.6			
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	12.3	—	nC	V <sub>DS</sub> = 30V, I <sub>D</sub> = 3A
Gate-Source Charge	Qgs	_	1.7	—	no	
Gate-Drain Charge	Q <sub>gd</sub>	_	1.9	_		
Turn-On Delay Time	tD(ON)	_	3.5	_		V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V RL ≅ 50Ω, R <sub>G</sub> ≅ 20Ω
Turn-On Rise Time	t <sub>R</sub>	_	4.1	_		
Turn-Off Delay Time	tD(OFF)		35		ns	
Turn-Off Fall Time	tF		11	_	]	
Body Diode Reverse Recovery Time	trr		18	_	ns	Is = 3A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>		12	_	nC	Is = 3A, dl/dt = 100A/µs

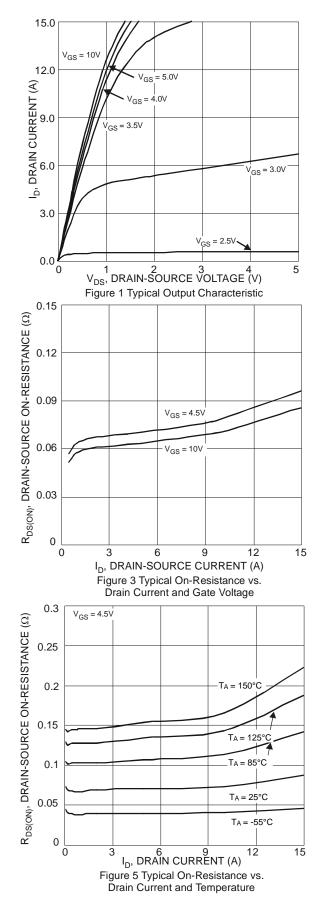
Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

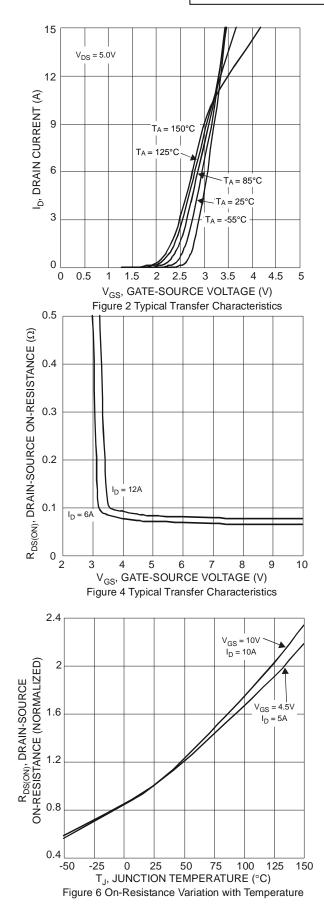
6. Device mounted on FR-4 substrate PC board, 202 copper, with 1inch square copper plate. 7. I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep  $T_J = +25^{\circ}C$ . 8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.



## DMN6070SSDQ

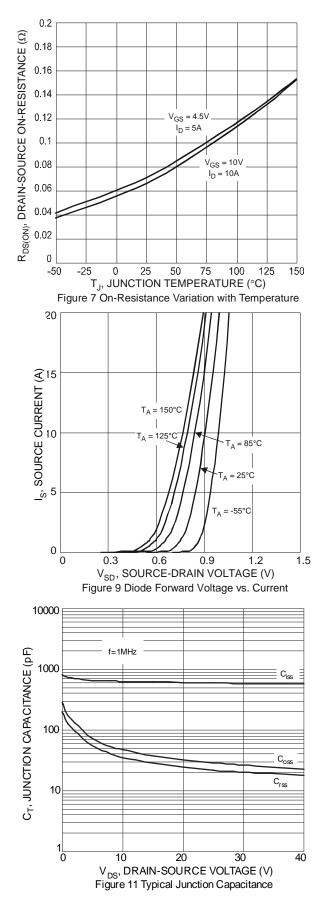


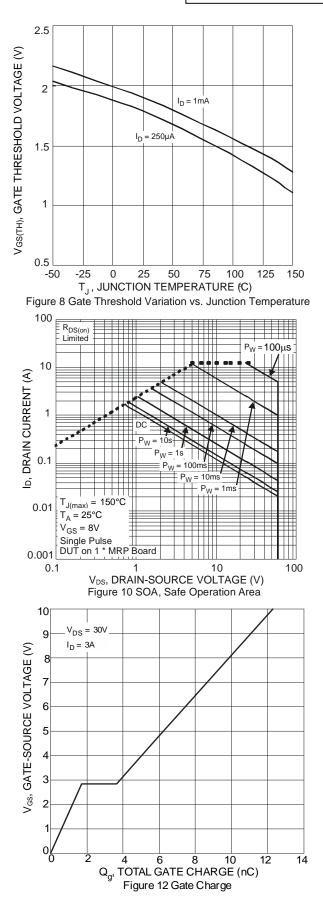


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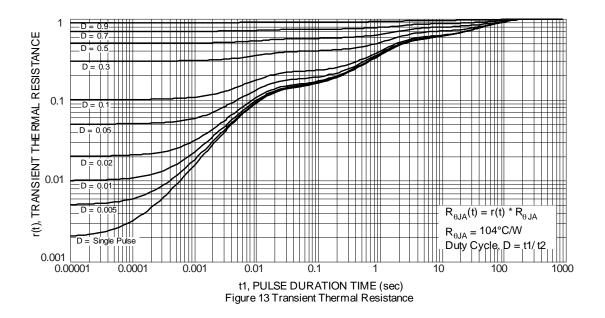






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Тур

1.45

0.15

0.40

0.20

4.90

6.00

3.85

3.90

1.27

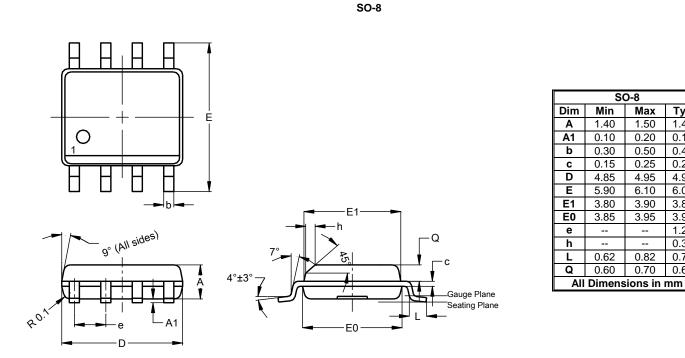
0.35

0.72

0.65

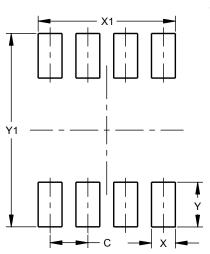
# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8

Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50



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